

ABSTRACT

In a conductive contact member typically used in fixtures for testing semiconductor devices and circuit boards having solder balls or terminals having solder deposited thereon, and electric sockets for semiconductor devices, a layer of highly electrically conductive material resistant to solder deposition is formed at least over a conductive contact part of the conductive contact member so that transfer of solder of the object to be tested onto the conductive contact member can be reduced and the number of possible contacts that can be effected before the cleaning of the solder deposition on the contact part becomes necessary can be increased. Therefore, the run time of the test line can be increased, and the maintenance cost can be reduced.

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